



Mono-crystalline silicon wafers manufactured by casting methods: Optoelectronic, structural and solar cell study



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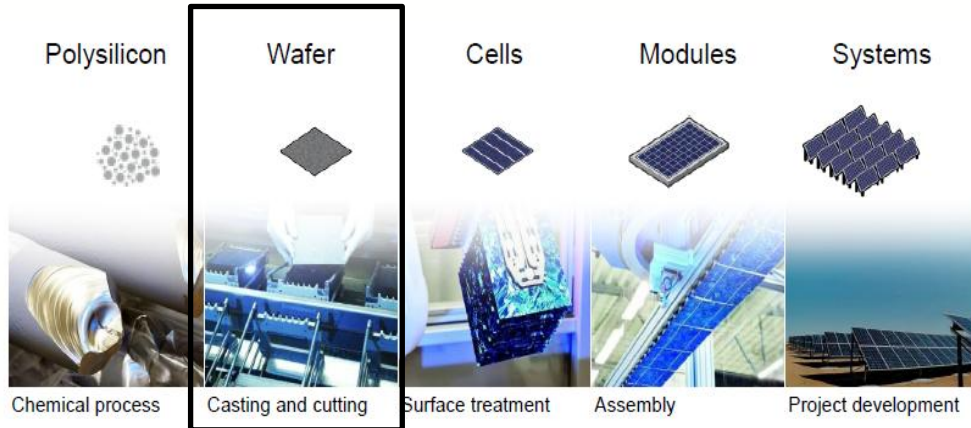


Outline

- 1) Introduction
- 2) *The Quasi-mono, pseudo-mono, mono-like ERA.*
- 3) Manufacturing mono-cast ingots: COST (seed recycling)
- 4) Summary and findings
- 5) Current status at DCWafers



Introduction to DC Wafers Investments, S.L.



- Multicrystalline wafers manufacturer
- Production capacity: 80 MW (1,6 mill./mo.)
- High quality standards

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PV market evolution

Some facts...

- Up to 50% price decrease
(Aug 10' - Aug 11')

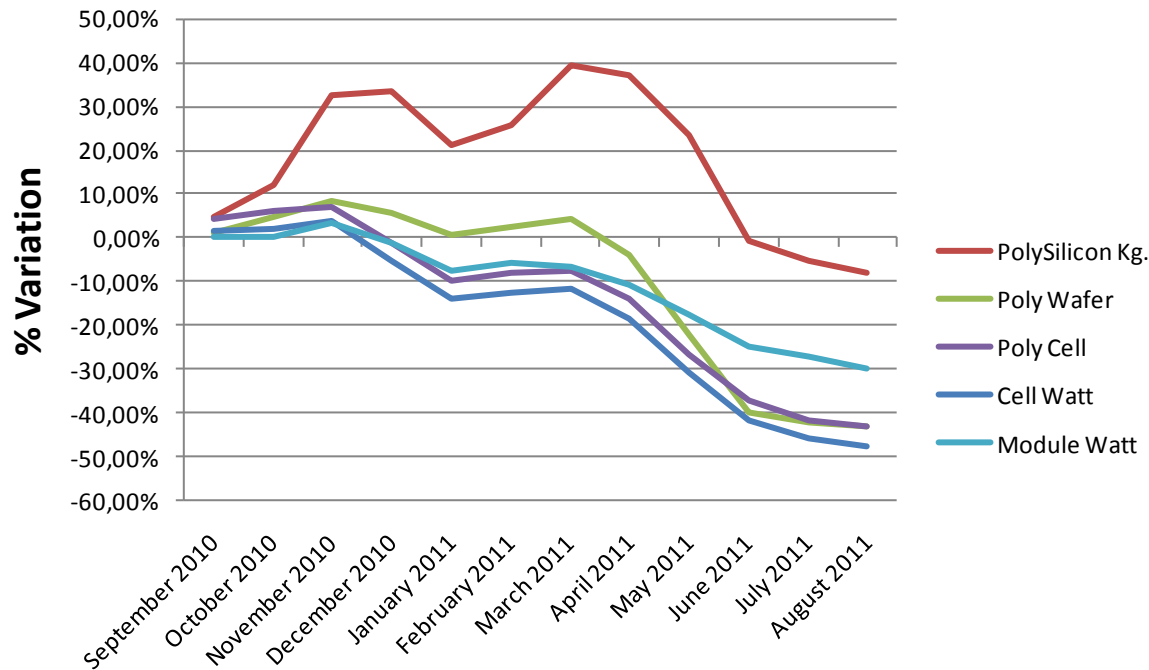
3.66 USD/wafer (March 10')
1.53 USD/wafer (October 11')

1.21 USD/Wp (March 10')
0.58 USD/Wp (October 11')

Restricted market: only high
efficiency materials and
devices are demanded

mc-Si wafer devaluation

PV Insights Aggregate Variations %





Quasi-mono, pseudo-mono, mono-like...

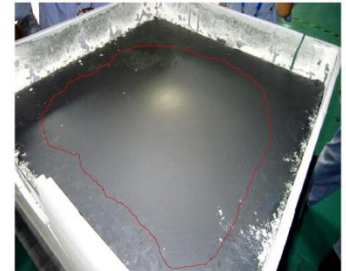


Casting Single Crystal Silicon: Novel Defect Profiles from BP Solar's Mono²™ Wafers

Nathan Stoddard^{1, a}, Bei Wu¹, Ian Witting², Magnus Wagener², Yongkook Park², George Rozgonyi² and Roger Clark¹



PV Production Equipment Conference, 14th April 2011



Jan 11'

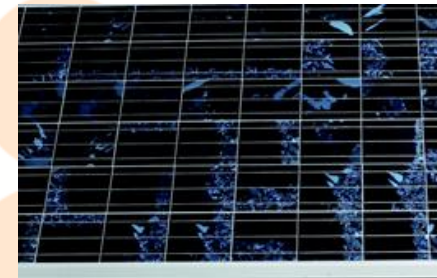
ReneSola claims new multi-crystalline wafer comparable in performance to mono



Jul 11'

Suntech Unveils Pluto and Mono/Multi Hybrid Modules

greentechsolar:



Oct 11'

GCL-Poly building major position in emerging 'quasi-mono' wafer market

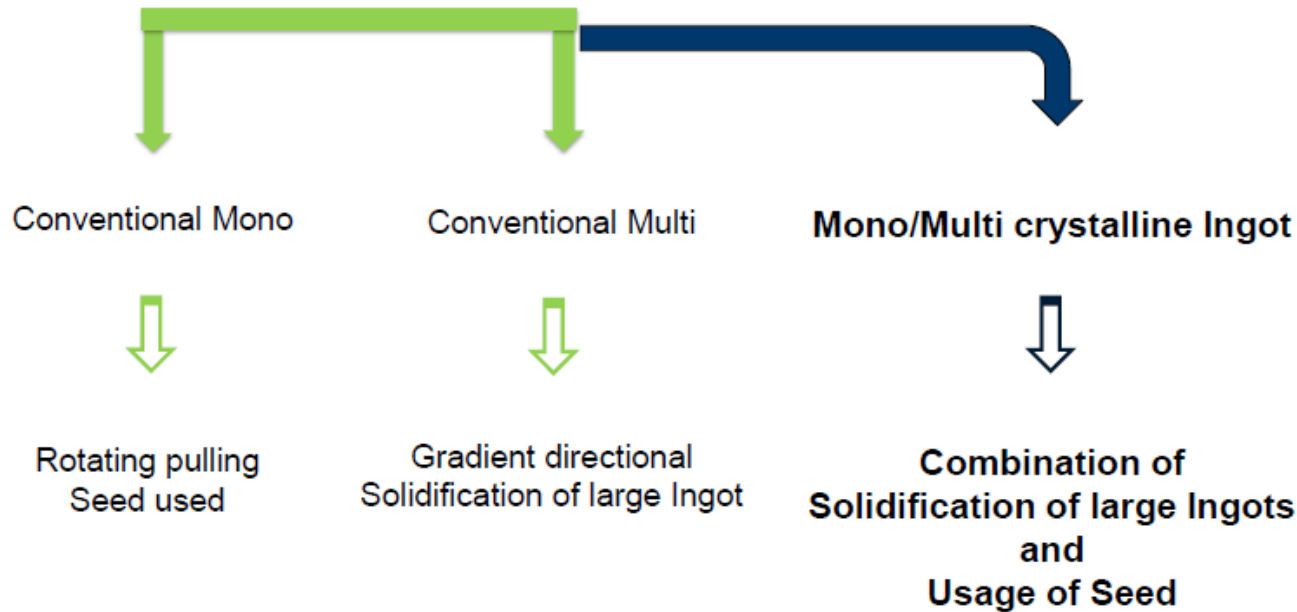


GT Advanced Technologies
Announces Commencement of DSS
MonoCast(TM) Beta Shipments and
Production Testing Partnership with
Korean PV Manufacturer Nexolon



Quasi-mono, pseudo-mono, mono-like...

Fundamentals...



Expected features...

- Lower LID than Cz-Si wafers.
- High efficiency due to Isc boost.
- High productivity as DSS/HEM methods are used lowering **cost** per watt.
- Lower breakage

Usage of Directional Solidification (DSS) and Heat Exchange Method (HEM) furnaces

Usage of seeds based on <100> orientated Cz-Si, preferably non-doped. Geometry and size-controlled

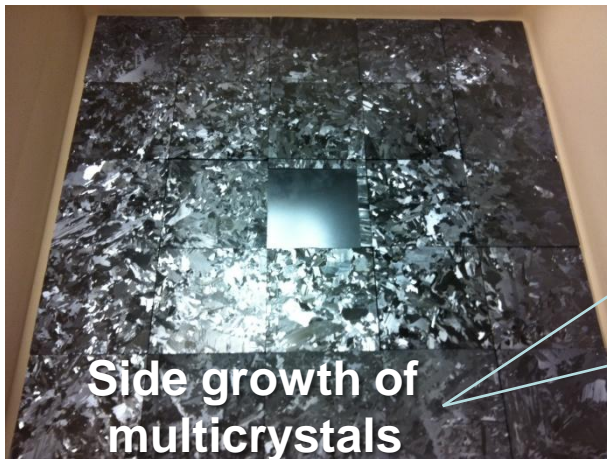
Controlled melting of the seed by thermal engineering (using both software and hardware approaches)

Optimization of the growth speed and temperature control during growth and annealing/cooling processes.

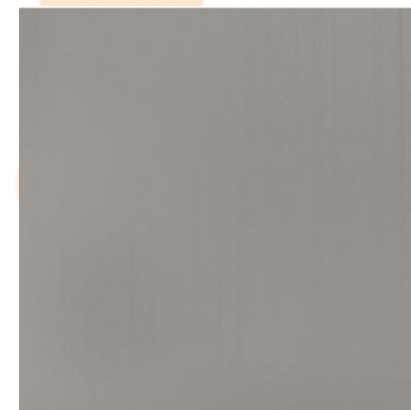
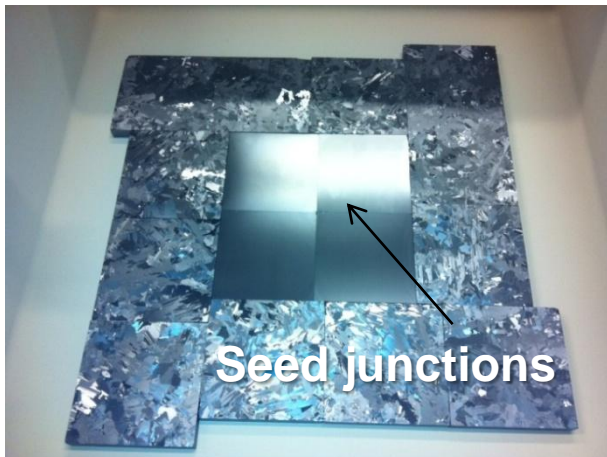


Manufacturing mono-cast ingots

Initial tests at DC Wafers (2010): general behavior of the mono seed



Average values:
EFF = 16.83 %
Isc = 8.53 A
Voc = 623 mV
FF= 77.14%

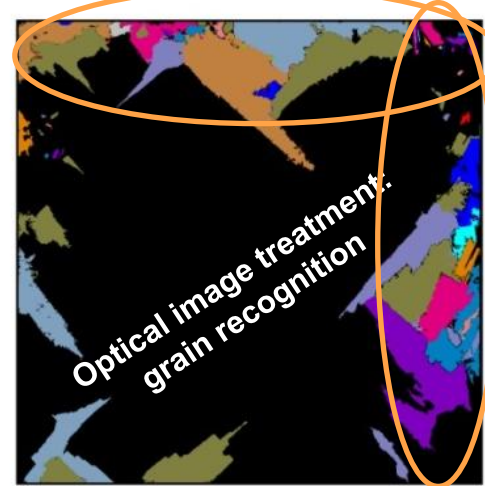


Average values:
EFF = 17.16 %
Isc = 8.55 A
Voc = 628 mV
FF= 77.78%

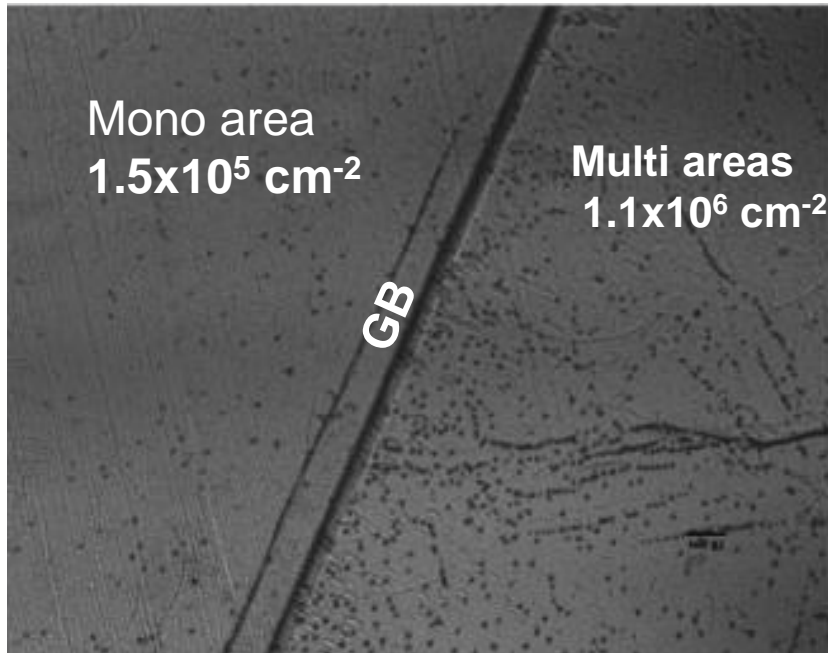
Central brick
99% (100) monocrystalline



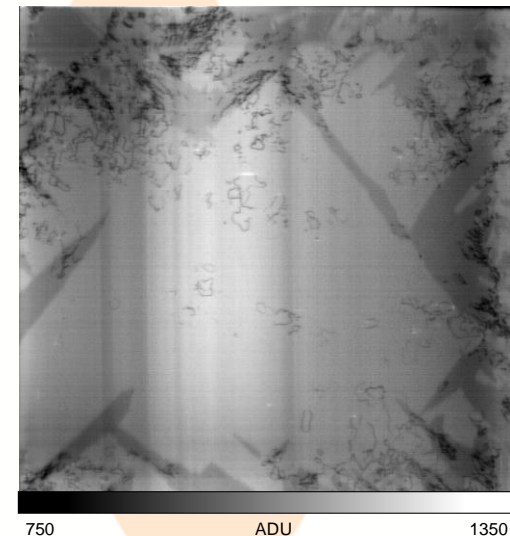
Massive Volume Manufacturing



Etch pit density (EPD) analysis



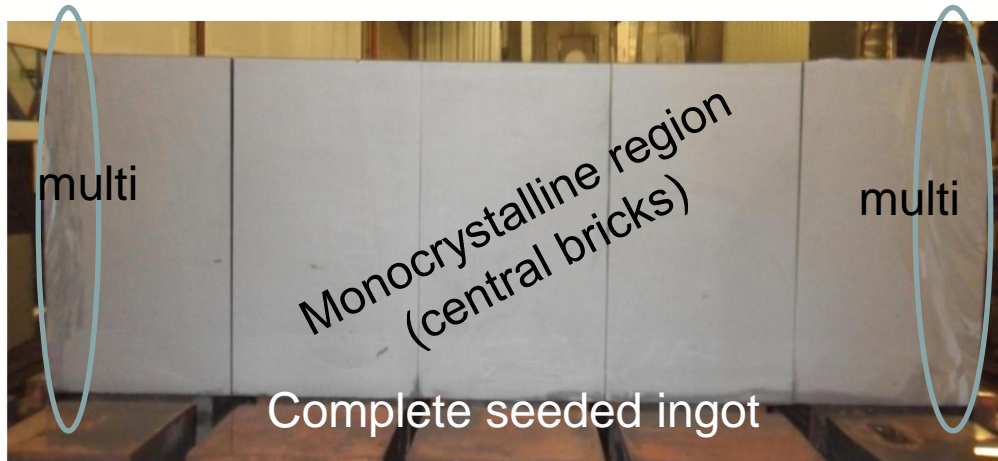
PL image of an as-cut wafer*



* In collaboration with Semilab



Our clasification



Mono casting (MC)
Monocrystalline 100%



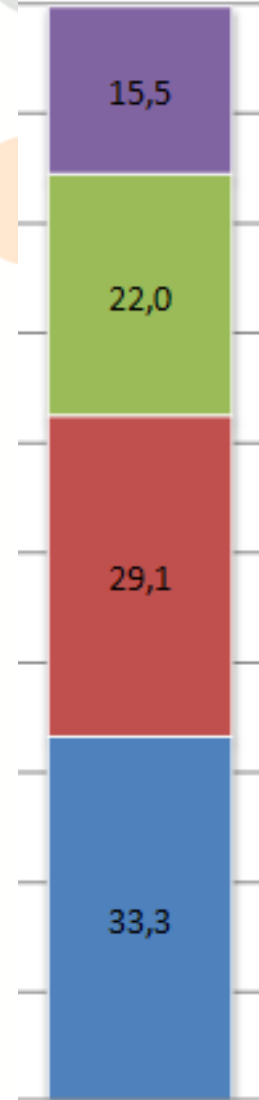
Quasi-mono (QM)
Monocrystalline >90%



DCWafers plus (DCW+)
Monocrystalline >75%



Mc-Si (multi o mono/multi)
Monocrystalline <75%





Manufacturing mono-cast ingots: *COST*

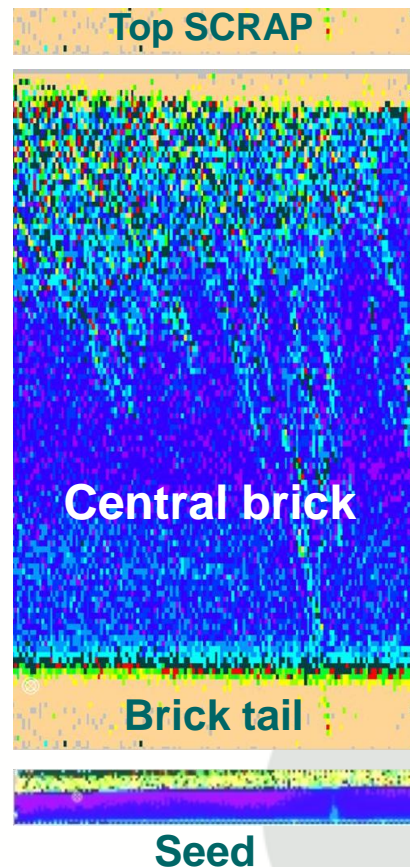
Typical uPCD lifetime behavior at brick level

COST ISSUES

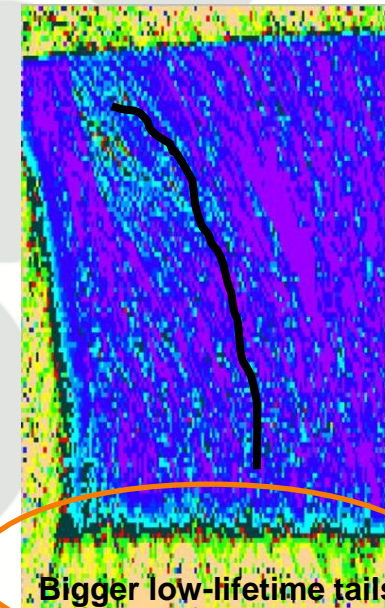
- Bigger tails
- Seed cost
- Cycle time

QUALITY ISSUES

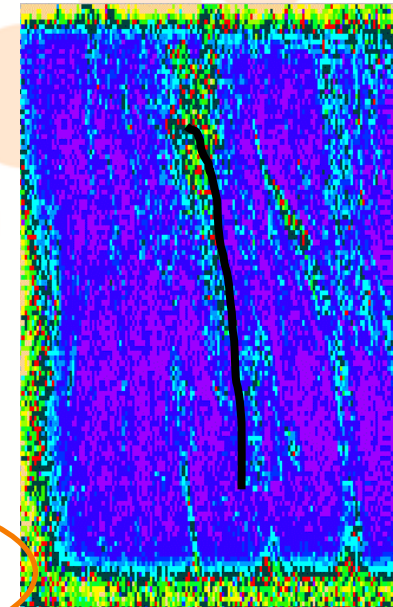
- Cell efficiency distribution
- ThermalStress



Seeded growth



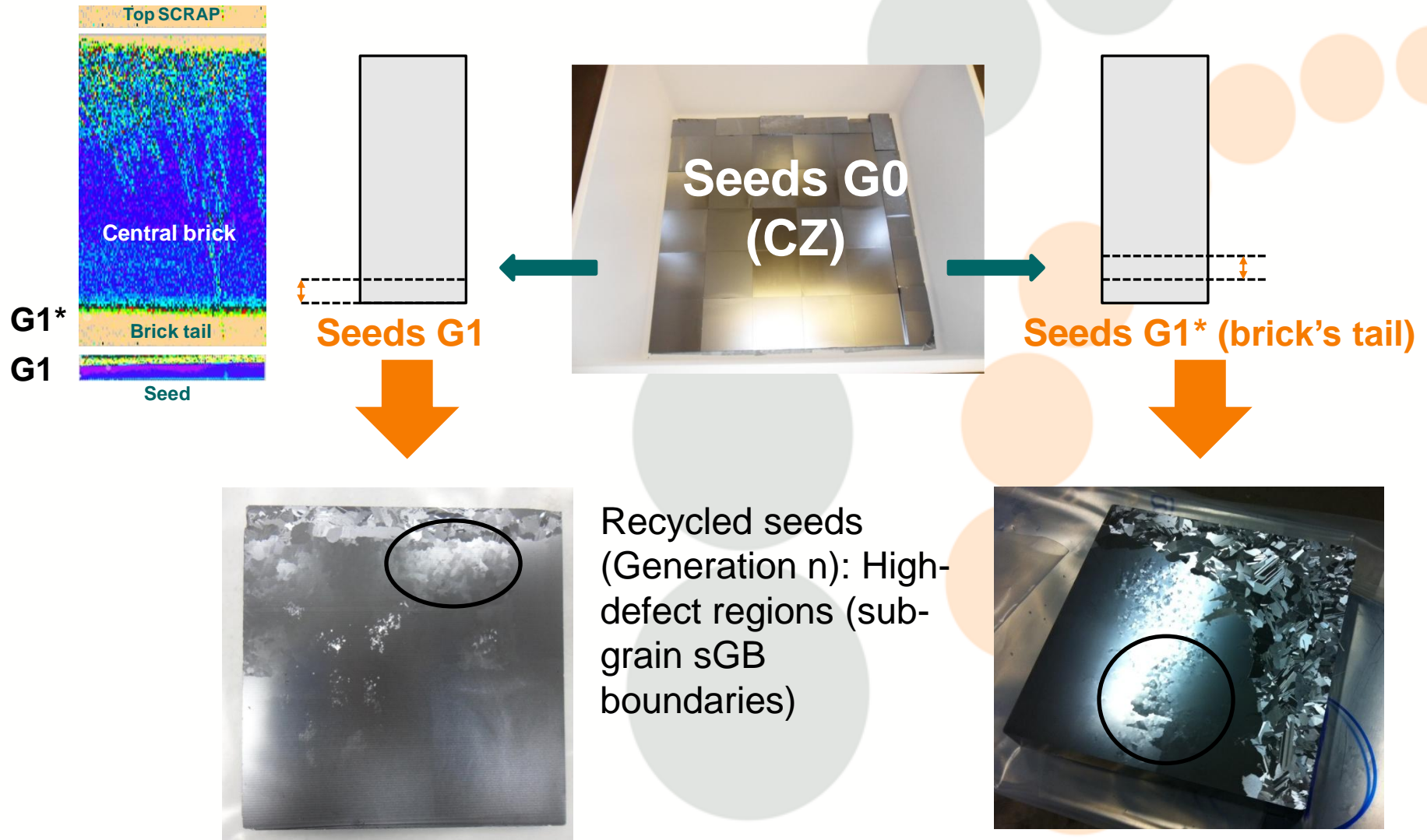
Conventional growth



Thermal gradients induce higher growth front curvature when using the seed-assisted approach



Manufacturing mono-cast ingots

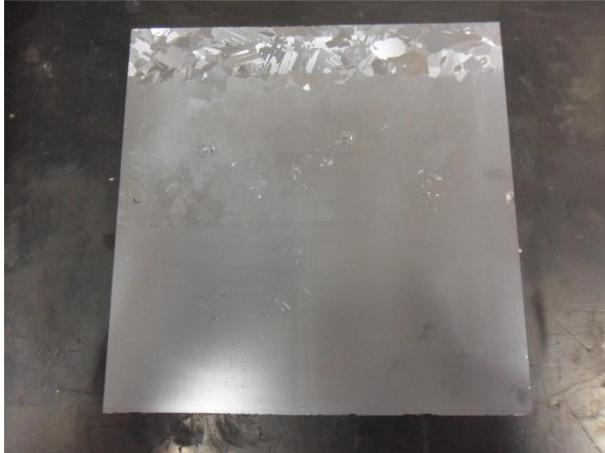




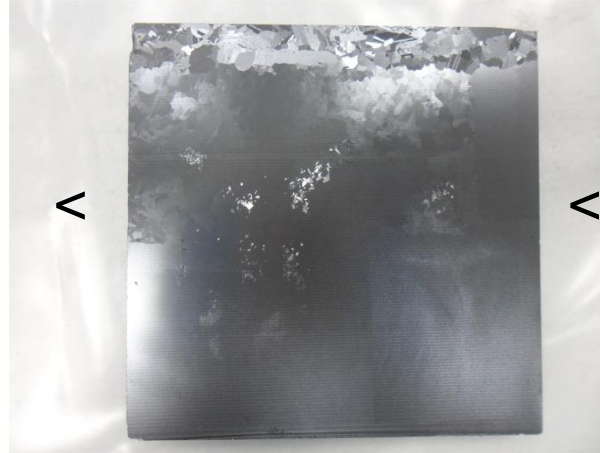
Manufacturing mono-cast ingots

side

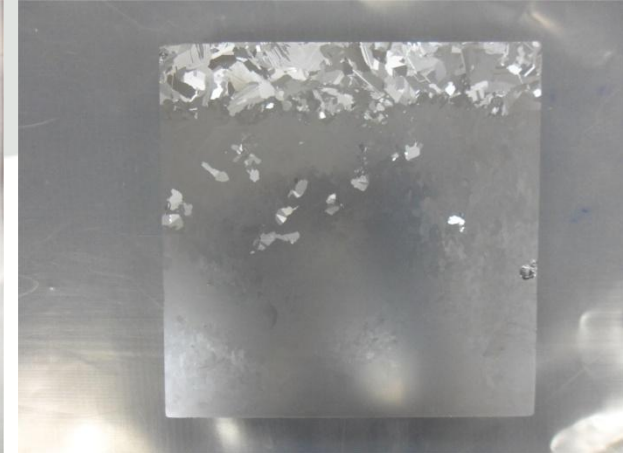
SEED G1



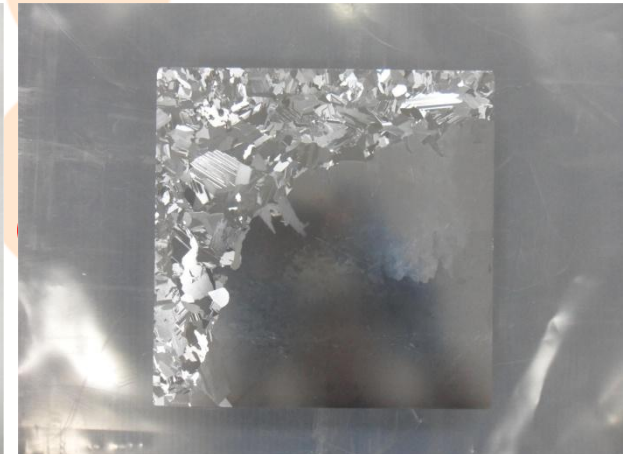
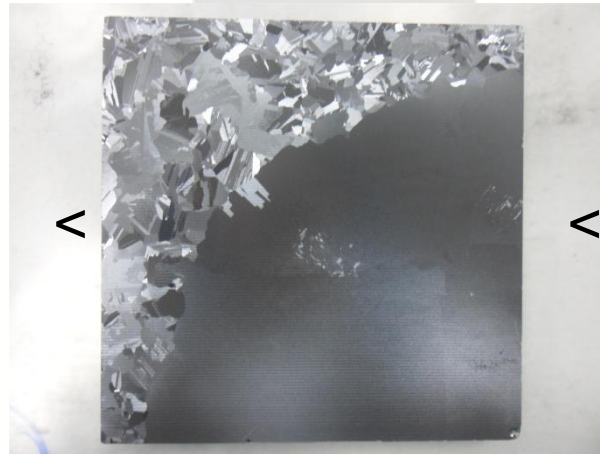
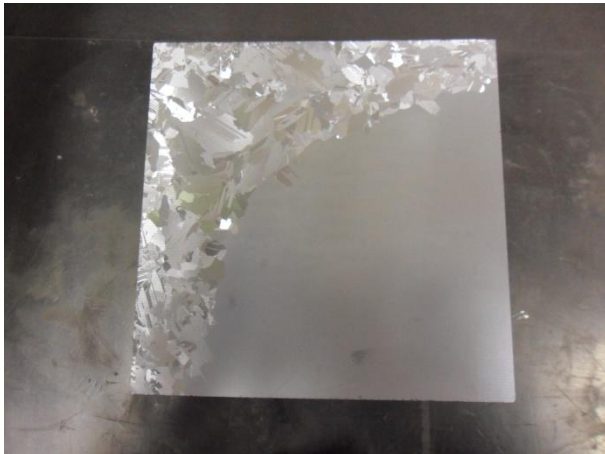
SEED G2



SEED G1*



corner



Larger defect areas but higher efficiency



Manufacturing mono-cast ingots

Brick 1

Seed G2

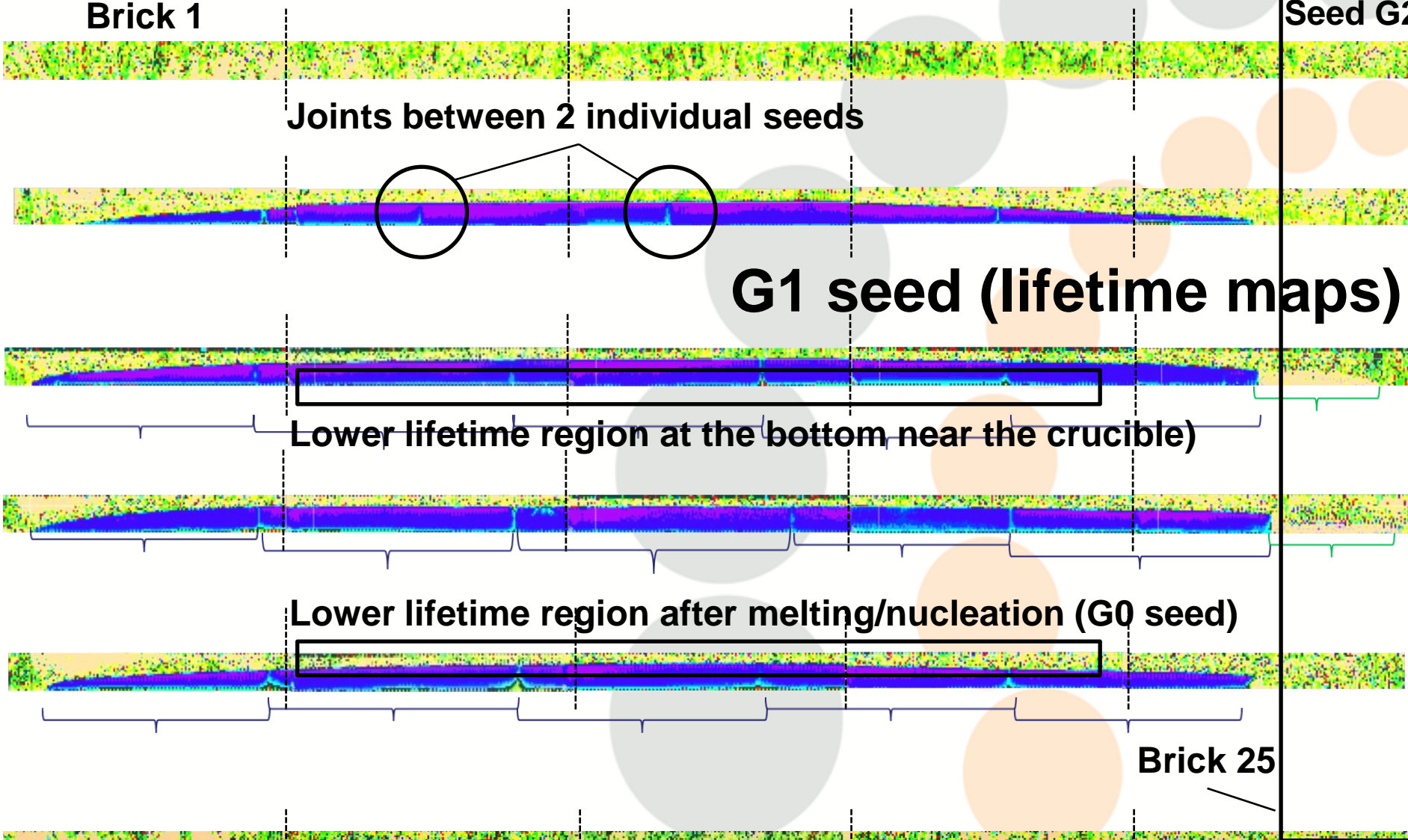
Joints between 2 individual seeds

G1 seed (lifetime maps)

Lower lifetime region at the bottom near the crucible)

Lower lifetime region after melting/nucleation (G0 seed)

Brick 25





Manufacturing mono-cast ingots

**All the previously detected low lifetime regions vs G1-seed are
markedly larger after one process**

G2 seed

The high lifetime regions of the previously used seed have now lost quality



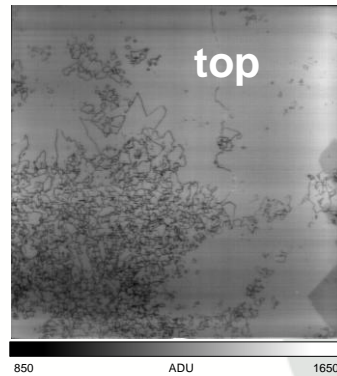
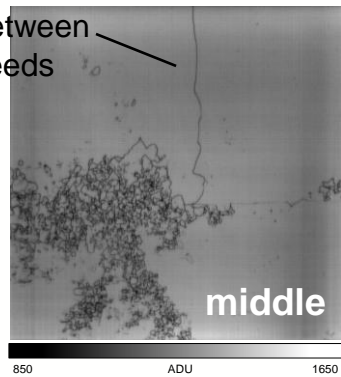
Manufacturing mono-cast ingots

Generation 2-based seeds

- **No MC (100% mono)** wafers after Generation 1
- Visible **defect structures** after KOH/HCl etching of the seeds.
- Lower average efficiency: **Isc as the most contributing factor to decrease efficiency**

G0 wafers (same brick)

Junction
between
seeds

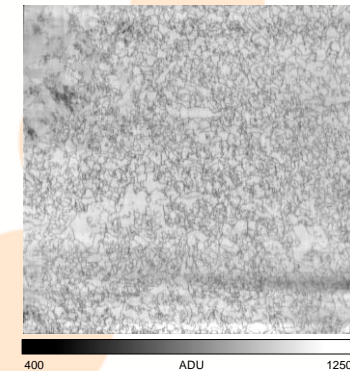


Seed recycling



New crystal

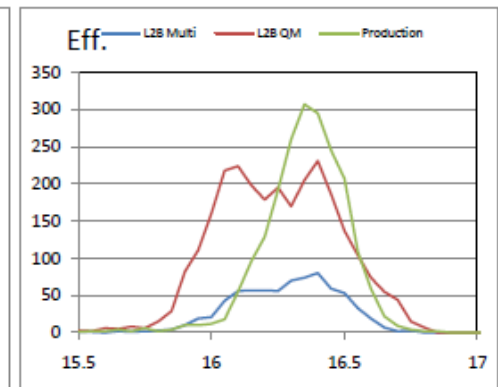
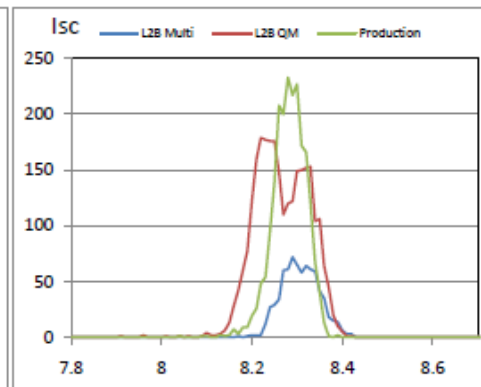
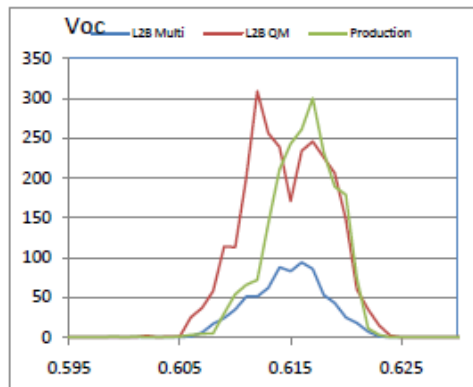
Gn wafers



**Isc and
efficiency
related to
bulk
defect
density**

Photoluminescence analysis in collaboration with SEMILAB

**QM: Eff =
16.27%**
**Multi region:
Eff = 16.29 %**
**Reference:
Eff = 16.37%**

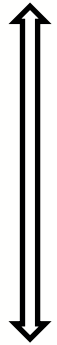




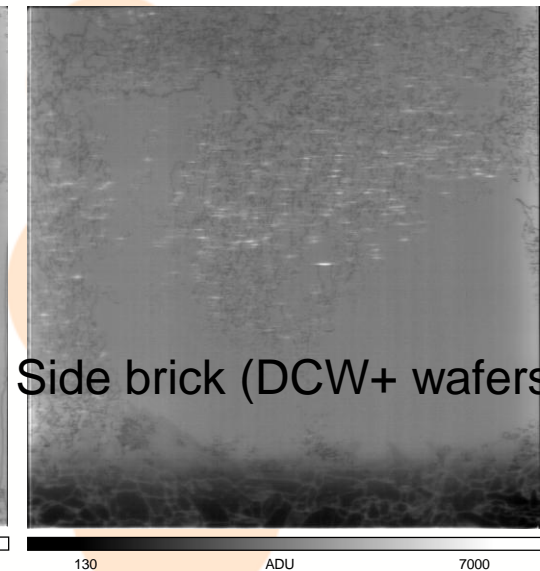
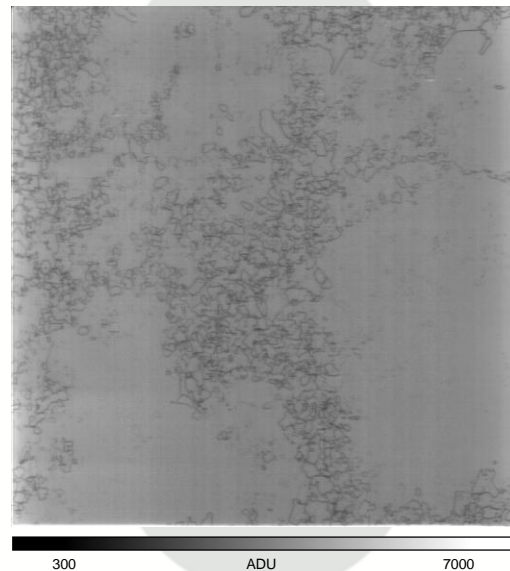
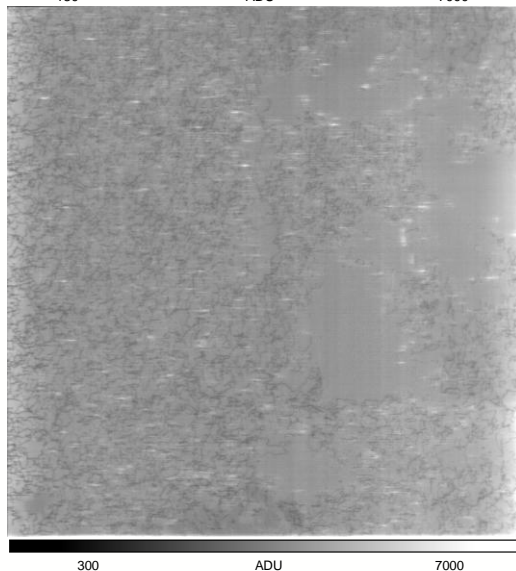
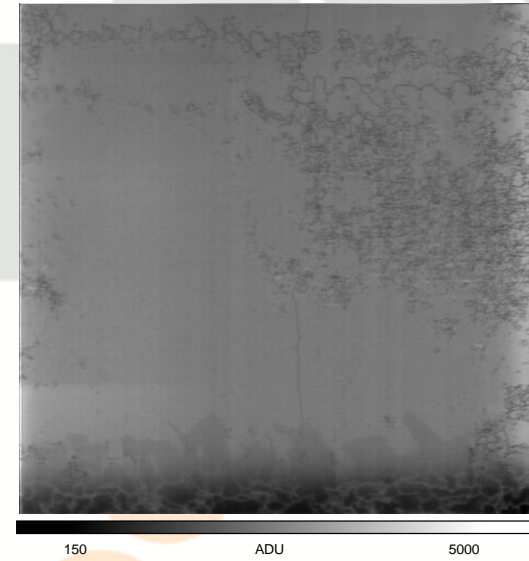
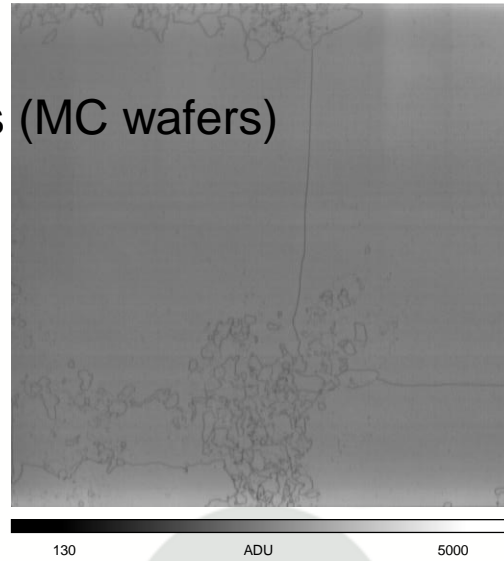
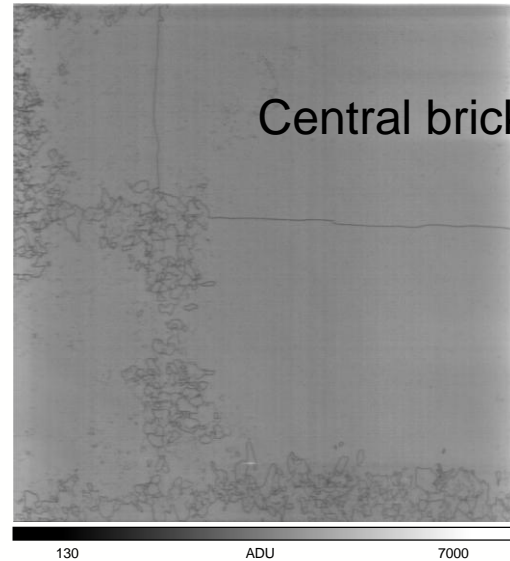
Manufacturing mono-cast ingots

Central bricks (MC wafers)

G1



G1*

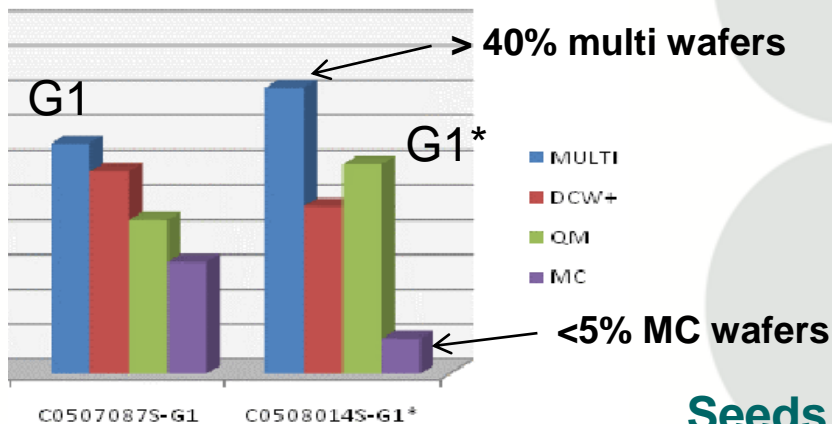
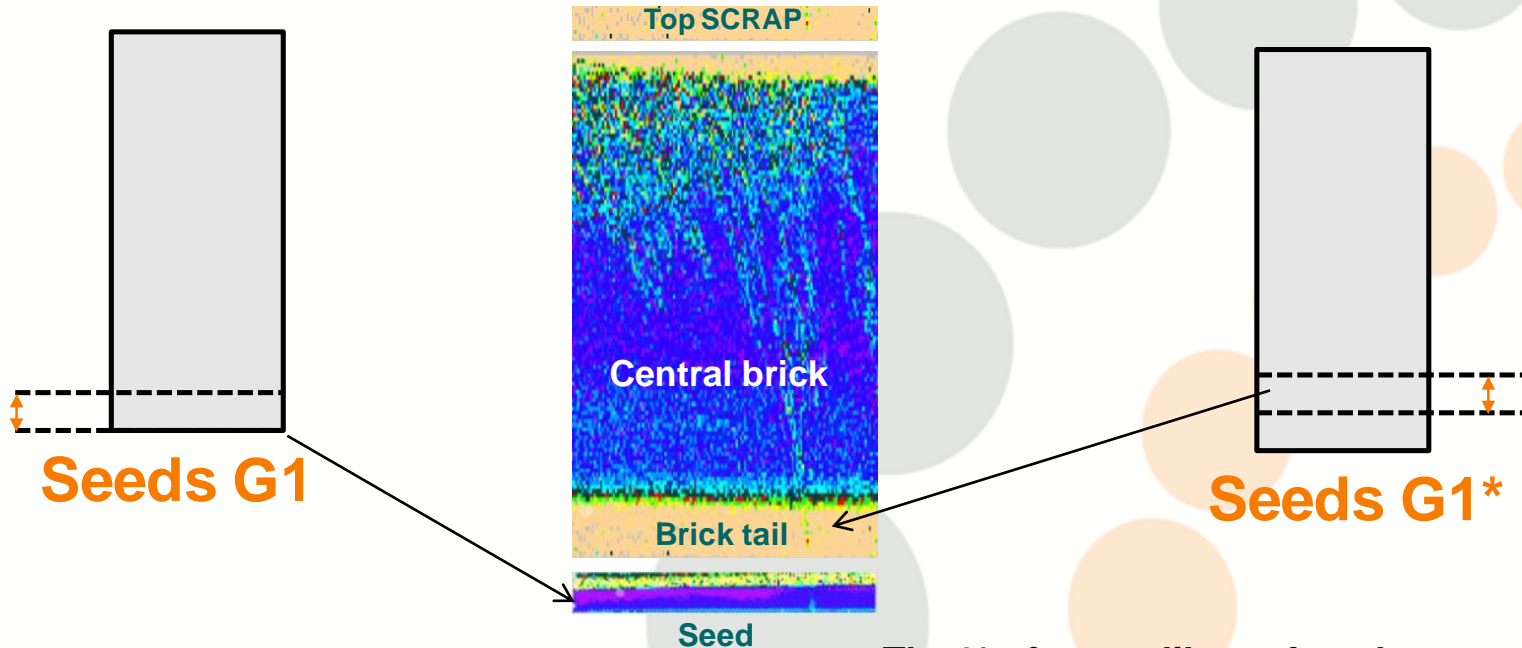


Side brick (DCW+ wafers)

Photoluminescence analysis in collaboration with SEMILAB



Manufacturing mono-cast ingots



The % of mono-like wafers decreases from G1 to G1*, but higher average efficiency was observed for G1* based seeds

Impurity effect (interstitial/defects decoration)

Seeds recycling: crystal defects or impurities?



Summary and findings

- High efficiency devices are more and more demanded by the hard and diffuse PV market.
- Quasi-mono based wafers entail one of the most attractive ways of satisfying those demands in a relatively easy and quick way.
- Solar cell/module customers still understanding the overall quasi-mono ingots performance (mono-like regions, average efficiency, even aesthetics...).
- Mass production are fully dependant on quality and availability of mono seeds and the cost related.
- Recycling of the seeds to reduce costs proven not to be an easy path due to dislocations from thermal stress

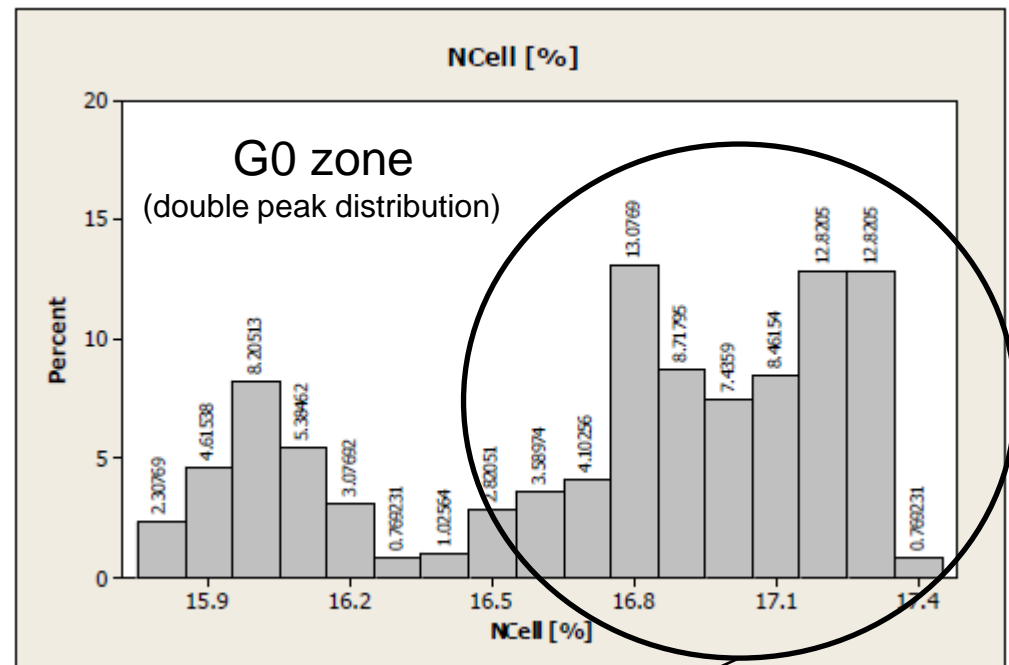


Summary and findings

Type of wafer	Isc/A	Voc/mV	Average EFF
G2 zone (ingot 1)	8.26	609	15.85
G0 zone (ingot 1)	8.45	623	16.80 (median: 16.90)
G1 (ingot 2)	8.33	612	16.12
G1* (ingot 3)	8.36	615	16.27

Values corresponding to equivalent samples taken from the respective ingots (DCW+, QM and MC)

Non-optimized iso-texturing process
(Isc up to 8.60 A can be reached)



65% of wafers exhibiting >16.80% eff



Current status at DCWafers

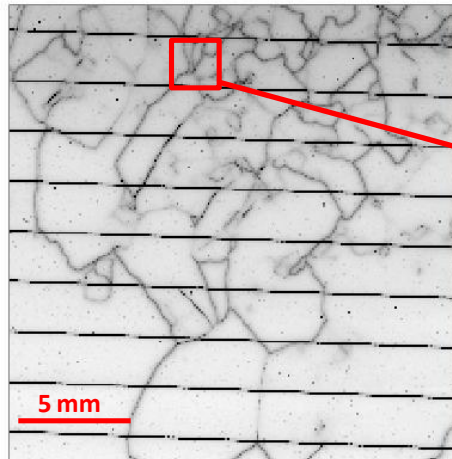
- Software and hardware modifications (recipe and furnace hot zone): average efficiency/ingot $>17\%$ using iso-texturing process and $>17.5\%$ using alkaline-based texturing.
- Study of the origin of the defects when recycling the seed: thermal shock during nucleation, effect of impurities coming from the crucible.
- Avoidance of low efficiency tails. Effect of carbon/oxygen impurities (fine FTIR analysis, LID).
- Use of alternative feedstock with encouraging yield/efficiency results.
- Cost reduction: increase efficiency by reusing seeds.
- Development of a pilot scale furnace (70 kg) sharing HEM and DSS features.



Current status at DCWafers

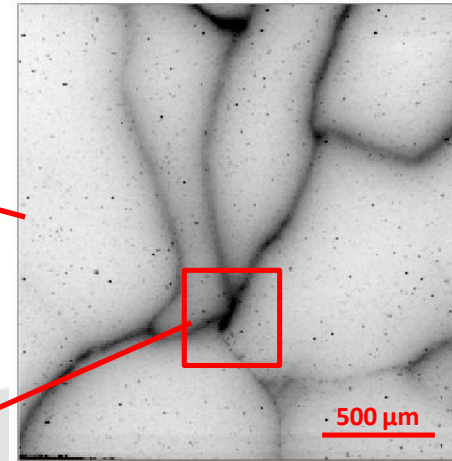
Light Beam Induced Current (LBIC) maps

Defect area
(G0-based
PV cell)



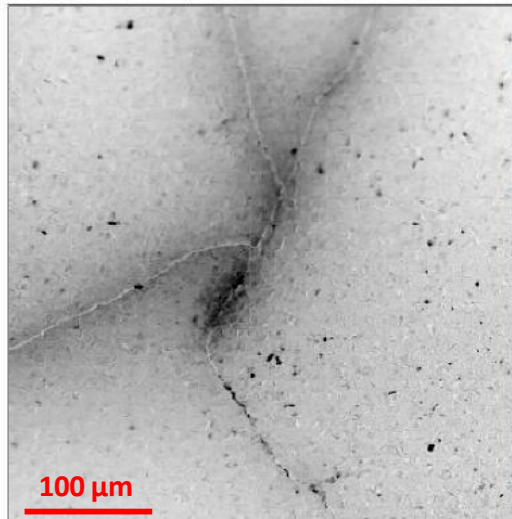
6.17E-4 A

1.40E-4 A



5.63E-4 A

1.72E-4 A



6.60E-4 A

3.02E-4 A

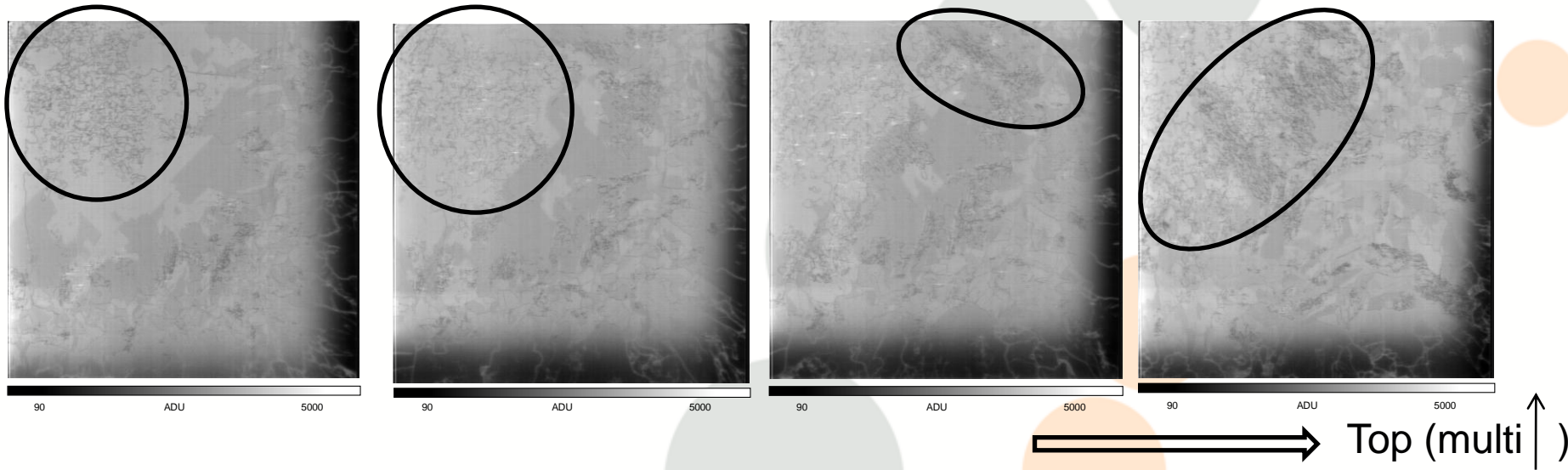
Extended defects with regions exhibiting different charge capture activity (effect of precipitated impurities)

The lower the I_{sc} values the more the density of highly active defects (from G0 wafers to Gn)



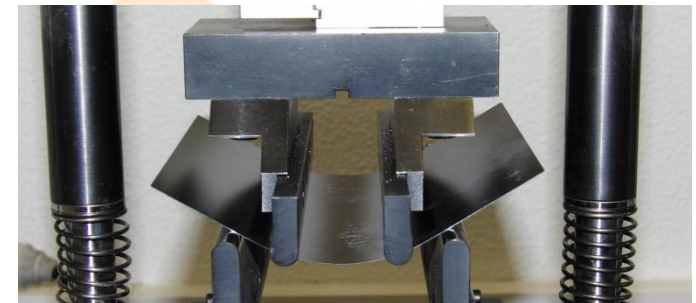
Current status at DCWafers

G0 (corner brick)



Defect density increases from the mono regions and near the mono/multi interfaces

Defect density increase from G0 to Gn seed-based ingots are in agreement with the occurrence of **lower mechanical resistance (fracture tension by FLBT analysis)** (*poster session J. Barredo et al.*)





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(Spain)



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Mr. Vijay Krish
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THANK YOU FOR YOUR ATTENTION!!



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